GigaDevice Semiconductor Inc.

Arm® Cortex®-M3/4/23/33 32-bit MCU

应用笔记

AN033

目录

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1. 简介

我们通常利用windows环境下的集成开发环境来开发单片机程序，例如keil或者IAR。本文介绍使在linux环境下用多个makefile管理RTOS工程的方法，在RTOS任务中实现一个LED闪烁功能。该方法可指定模块或文件进行编译。

2. 开发环境介绍

开发环境准备：

- 硬件平台：GD32F303-Test-V1.1
- 编译环境：ubuntu16.04
- 工具链： gcc-arm-none-eabi, gcc-arm-none-objcopy
- 烧录工具：SEGGR J-FlashVV6.50b

2.1. 安装 ubuntu 虚拟机

虚拟机软件下载地址：https://www.vmware.com/cn/products/workstation-pro/workstation-pro-evaluation.html.

双击运行安装包文件,根据安装向导，如*图 2-1. ubuntu 虚拟机安装向导 1* 点击下一步，选择默认的设置。

图 2-1. ubuntu 虚拟机安装向导 1

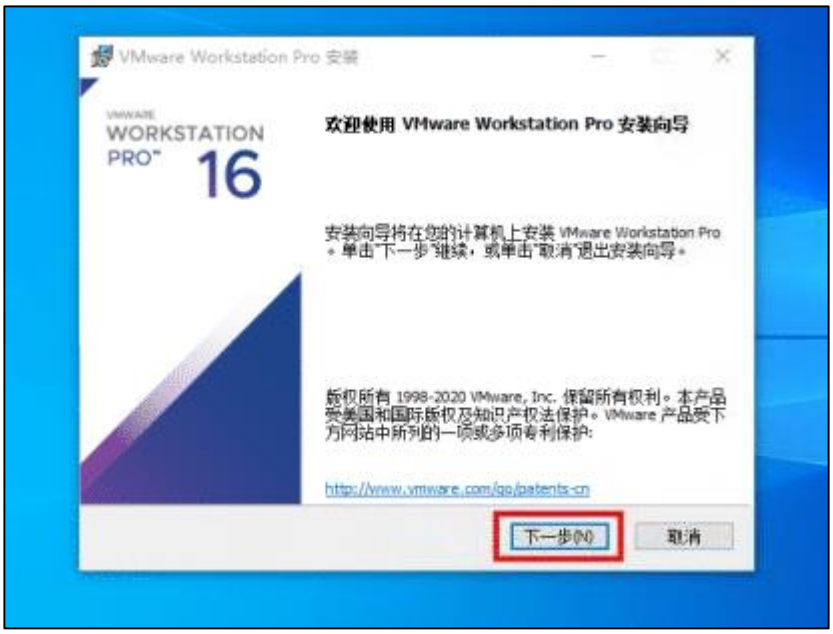


图 2-2. ubuntu 虚拟机安装向导 2

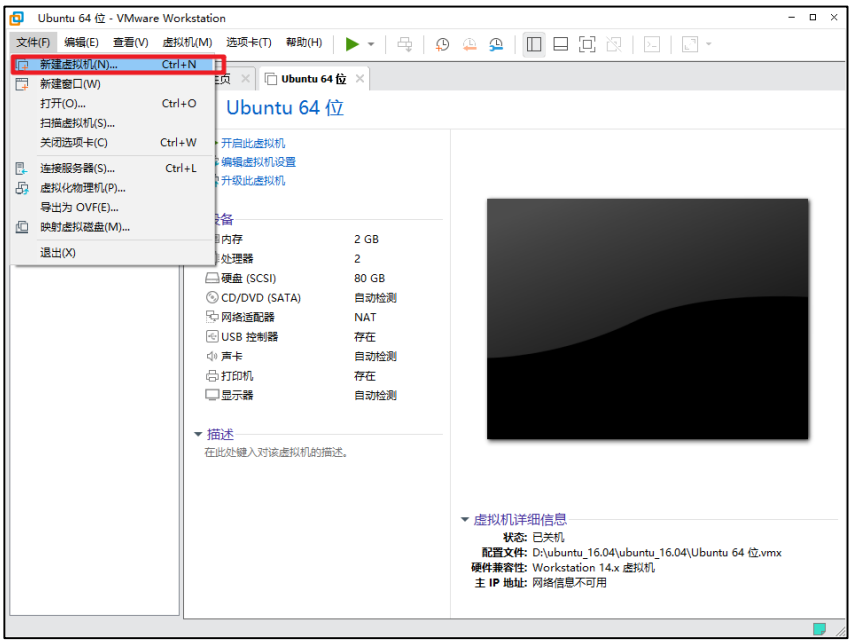
点击“完成”，完成安装.。

图 2-3. ubuntu 虚拟机安装向导 3

在 VMware 中安装 ubuntu，下载 ubuntu 镜像文件，下载地址：http://mirrors.aliyun.com/ubuntu-releases/16.04/

Ubuntu 镜像下载完成后，打开虚拟机，点击“文件 --> 新建虚拟机”。

图 2-4. ubuntu 虚拟机安装向导 4

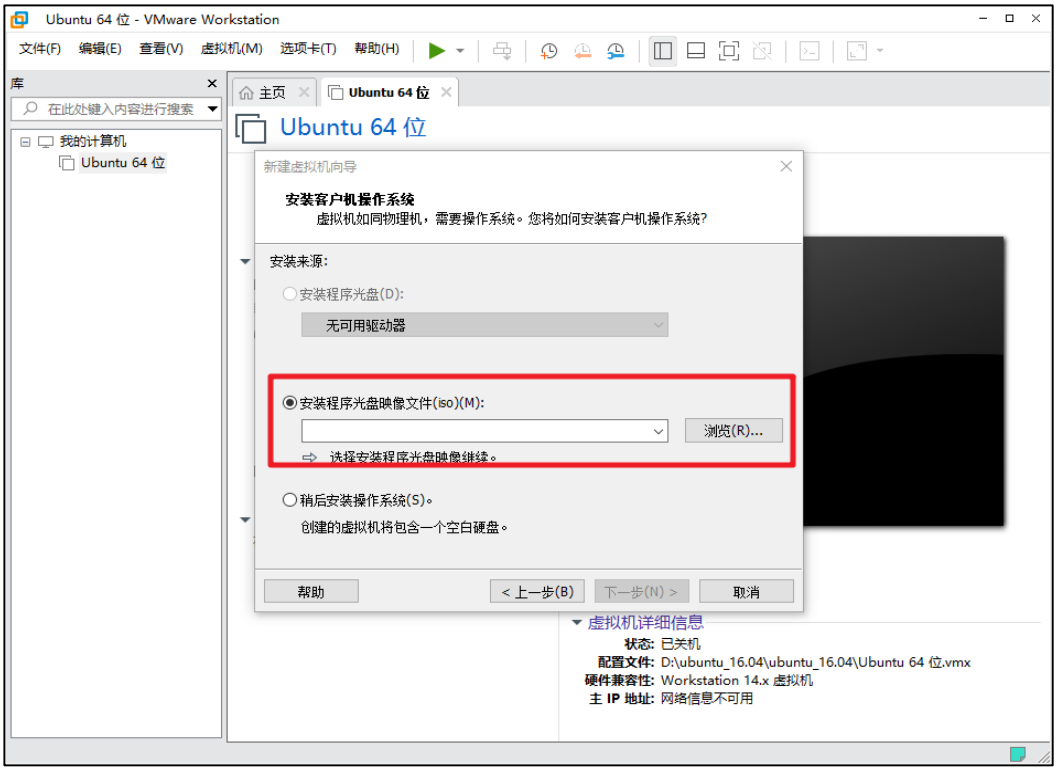


使用默认设置，点击“下一步”。

图 2-5. ubuntu 虚拟机安装向导 5

选择之前下载的 ubuntu 镜像文件，继续使用默认设置点击“下一步”。

图 2-6. ubuntu 虚拟机安装向导 6



开始安装虚拟机系统，点击开始此虚拟机，第一次启动时间较长，选择默认设置直到启动完成即可。

图 2-7. ubuntu 虚拟机安装向导 7

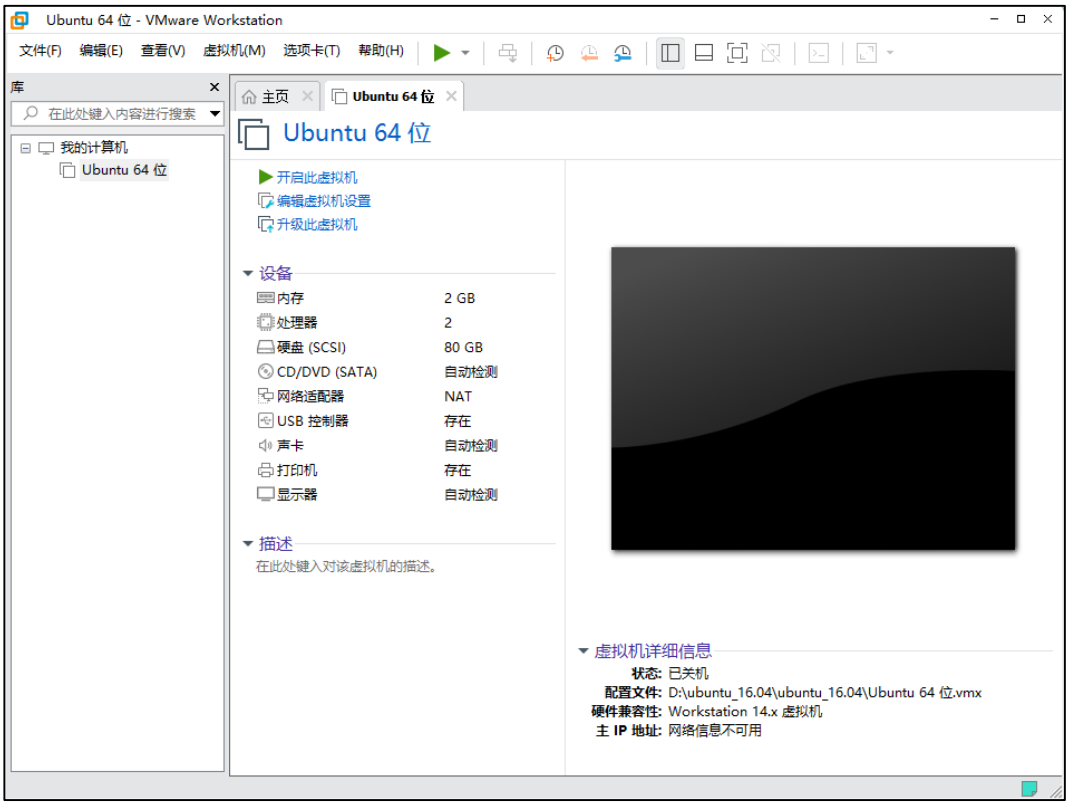
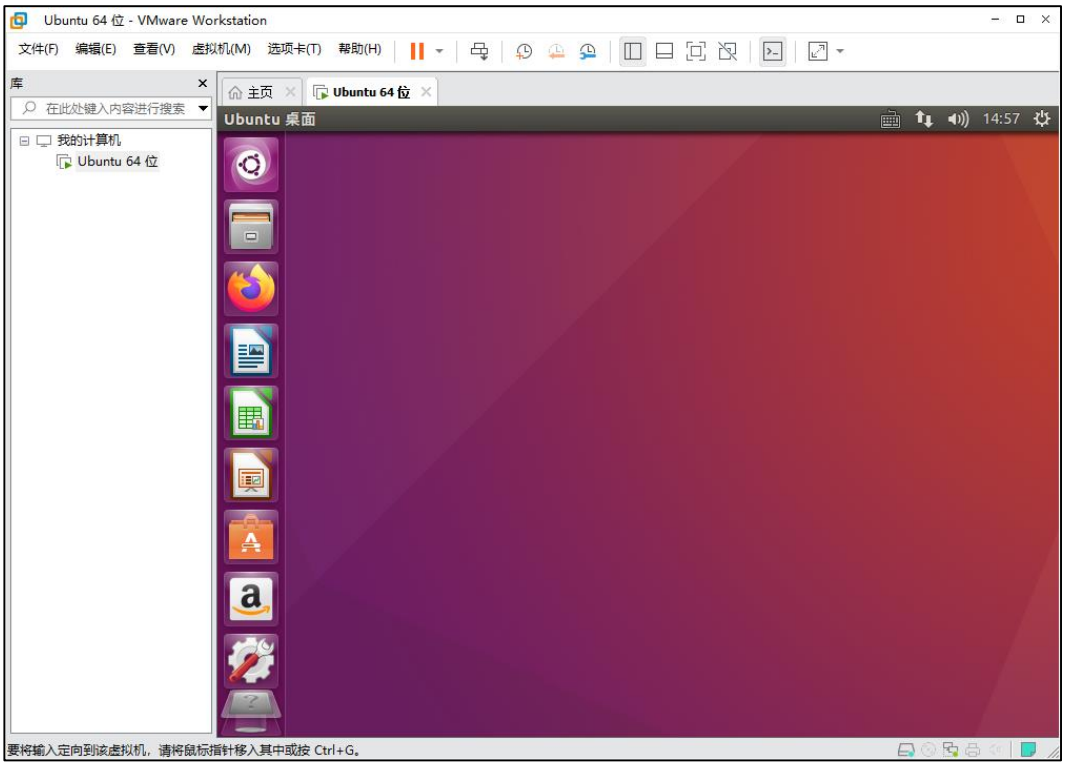


*图 2-8. ubuntu 虚拟机启动完成*是 ubuntu 虚拟机启动完成后的界面。

图 2-8. ubuntu 虚拟机启动完成

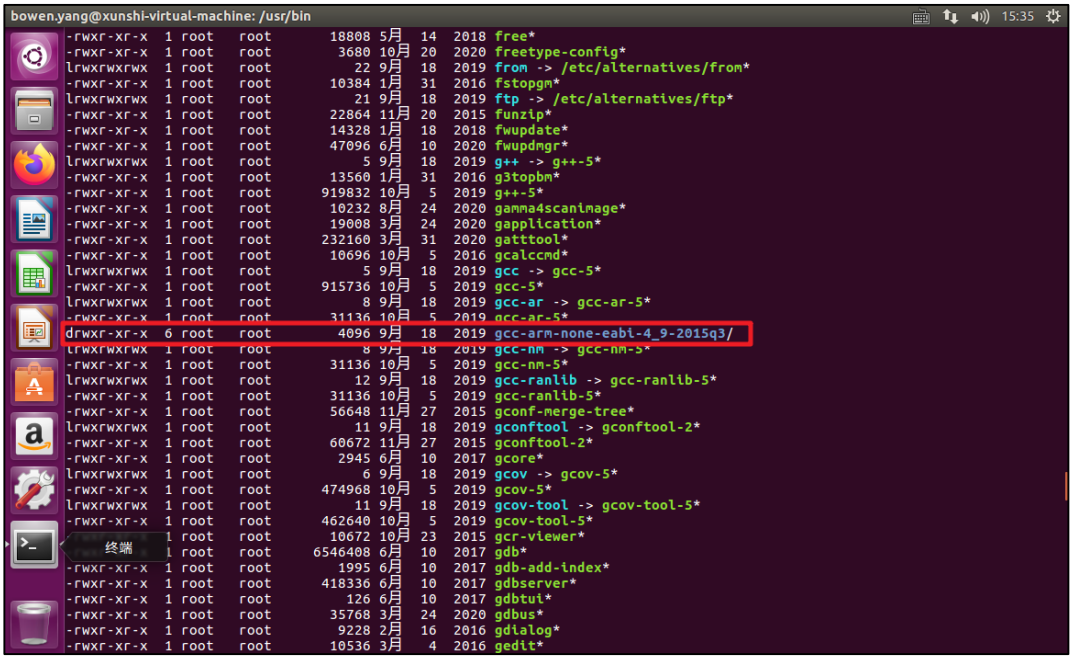


2.2. 安装工具链

使用编译好的工具链，下载地址：https://launchpad.net/gcc-arm-embedded/+download

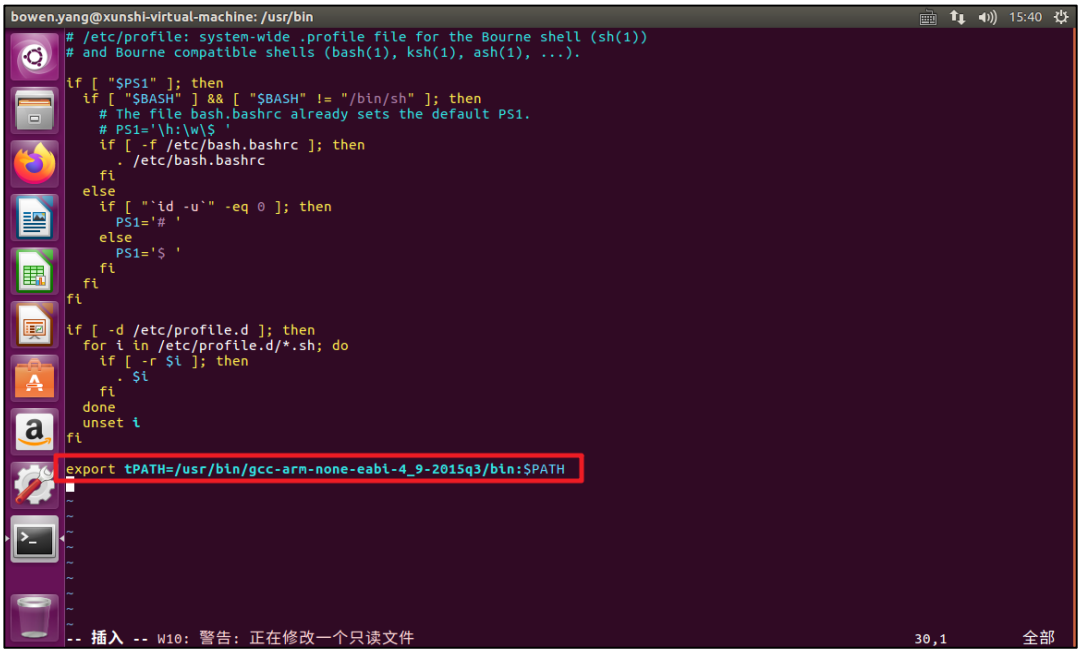
将下载好的工具链放到 ubuntu 的/usr/bin/目录下解压，解压后得到 gcc-arm-none-eabi-4_9-2015q3/目录。如*图 2-9. GCC 工具链所在目录*。

图 2-9. GCC 工具链所在目录



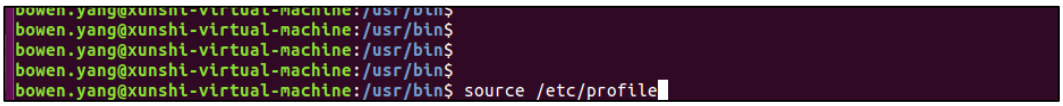
接下来配置 linux 系统环境变量，在/etc/profile 文件最后一行指定 GCC 工具链目录。

图 2-10. 配置环境变量



添加完成后执行命令：source /etc/profile 使环境变量生效，不用重启虚拟机。

图 2-11. 环境变量生效



完成后再任意目录下输入命令 arm 加 tab 键，如果系统自动弹出工具链则列表代表安装成功，如*图 2-12. 交叉工具链列表*，弹出的工具链列表中有我们需要的 arm-none-eabi-gcc 和 arm-none-eabi-objcop。

图 2-12. 交叉工具链列表

3. 建立工程

3.1. 建立工程目录

将所需要编译的 RTOS 工程代码放到 D:\share\RTX\ubuntu，如图*图 3-1. 工程代码目录*。

图 3-1. 工程代码目录

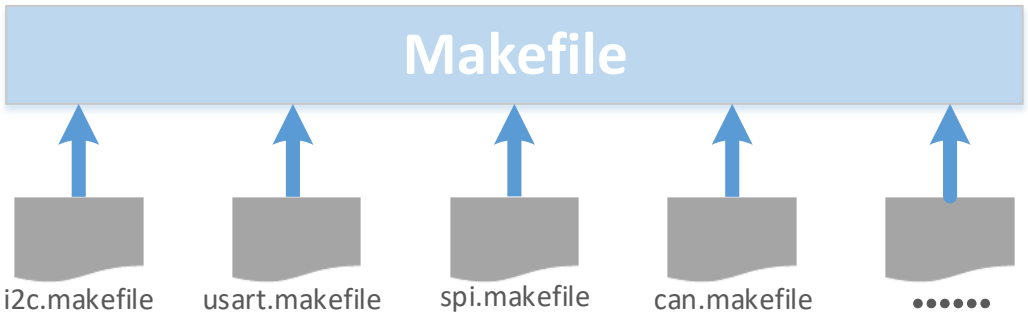
目录结构如下所示,每个 source 目录下都需要一个 makefile 文件。

```
├──APP
|    ├──include
|    └──source
├──CMSIS
|    ├──GCC
|    ├──include
|    └──source
├──Core
|    ├──include
|    └──source
├──Device
|    ├──include
|    └──source
└──SourceGroup
     ├──include
     └──source
```

3.2. Makefile 文件编写

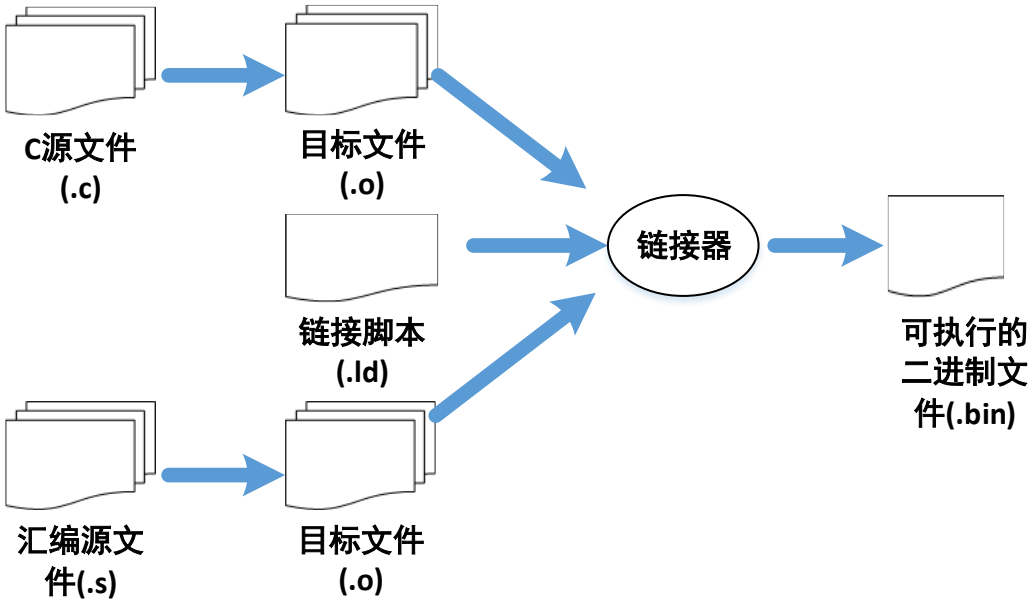
使用顶层 makefile 管理各子目录下的 makefile，如图*图 3-2. 图示*

图 3-2. 图示



整体编译流程如图*图 3-3. 编译流程*。

图 3-3. 编译流程



顶层 makefile 编写如下：

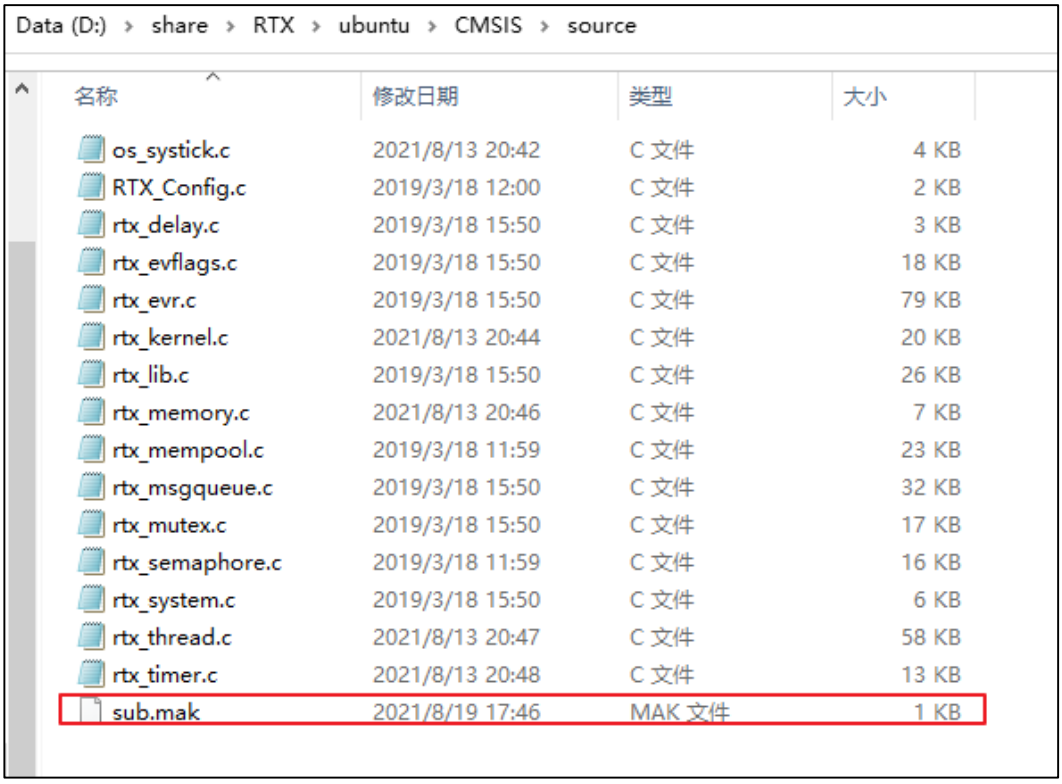
表 3-1. 顶层 makefile 编写

```
CROSS_COMPILE=arm-none-eabi-

CC                  = $(CROSS_COMPILE)gcc
OBJCOPY         = $(CROSS_COMPILE)objcopy

TOP=$(shell pwd)
INC_FLAGS = -I$(TOP)/Device/include \
                    -I$(TOP)/Core/include \
                    -I$(TOP)/APP/include \
                    -I$(TOP)/Stdlib/include \
                    -I$(TOP)/CMSIS/include

CC_FLAGS    =    -W    -Wall    -g    -mcpu=cortex-m4    -mthumb    -D    GD32F30X_HD    -D
USE_STDPERIPH_DRIVER $(INC_FLAGS) -O0 -std=gnu11
```

```
CC_ASM_FLAGS = -mthumb -mcpu=cortex-m4 -g -Wa,--warn

CC_LD_FLAGS += -mthumb -mcpu=cortex-m4
CC_LD_FLAGS += -Wl,--start-group -lc -lm -Wl,--end-group -specs=nosys.specs -static -Wl,-cref,-u,Reset_Handler-Wl,-Map=RTX_Project.map-Wl,--gc-sections-Wl,--defsym=malloc_getpagesize_P=0x80

LD_PATH = -TDevice/source/gd32f30x_flash.ld
#用于指示该模块是否参与编译
SUPPORT_IIC = yes
SUPPORT_SPI = yes
SUPPORT_CAN = yes
SUPPORT_KEY = no
#指定需要编译的源文件
include APP/source/sub.mak
include CMSIS/source/sub.mak
include Device/source/sub.mak
include SourceGroup/source/sub.mak

TARGET = RTX_Project

.PHONY: clean all
#替换为.o
C_OBJ = $(C_SRC:%.c=%.o)
ASM_OBJ = $(ASM_SRC:%.s=%.o)

all:$(C_OBJ) $(ASM_OBJ)
	$(CC) $(C_OBJ) $(ASM_OBJ) $(LD_PATH) -o $(TARGET).elf $(CC_LD_FLAGS)
	$(OBJCOPY) $(TARGET).elf  $(TARGET).bin -Obinary

%.o:%.c
	$(CC) -c $(CC_FLAGS) -o $@ $<
%.o:%.s
	$(CC) -c $(CC_ASM_FLAGS) -o $@ $<

clean:
	rm -rf *.o $(C_OBJ) $(ASM_OBJ) $(TARGET) *.bin *.map *.elf
```

分别在 APP、CMSIS、Core、Device、SourceGroup 目录下建立 sub.mak 文件，所有目录下的 sub.mak 文件编写方式都一样，这里介绍 CMSIS/source 目录下的下的 sub.mak。

图 3-4. sub.mak 所在目录



在 sub.mak 文件中指定本目录中需要编译的文件，makefile 编写如下:

表 3-2. 子目录 sub.mak 编写

```
CMSIS_PATH = CMSIS/source
C_SRC += $(CMSIS_PATH)/os_systick.c \
                $(CMSIS_PATH)/RTX_Config.c \
                $(CMSIS_PATH)/rtx_delay.c \
                $(CMSIS_PATH)/rtx_evflags.c\
                $(CMSIS_PATH)/rtx_evr.c \
                $(CMSIS_PATH)/rtx_kernel.c \
                $(CMSIS_PATH)/rtx_lib.c \
                $(CMSIS_PATH)/rtx_memory.c \
                $(CMSIS_PATH)/rtx_mempool.c \
                $(CMSIS_PATH)/rtx_msgqueue.c \
                $(CMSIS_PATH)/rtx_mutex.c \
                $(CMSIS_PATH)/rtx_semaphore.c \
                $(CMSIS_PATH)/rtx_system.c \
                $(CMSIS_PATH)/rtx_thread.c \
                $(CMSIS_PATH)/rtx_timer.c

ifeq ($(SUPPORT_KEY), yes)
C_SRC += $(AUDIO_PATH)/rtx_keymanager.c
endif
```

```
ASM_SRC += $(CMSIS_PATH)/../GCC/irq_cm3.s
```

3.3. 编译和测试

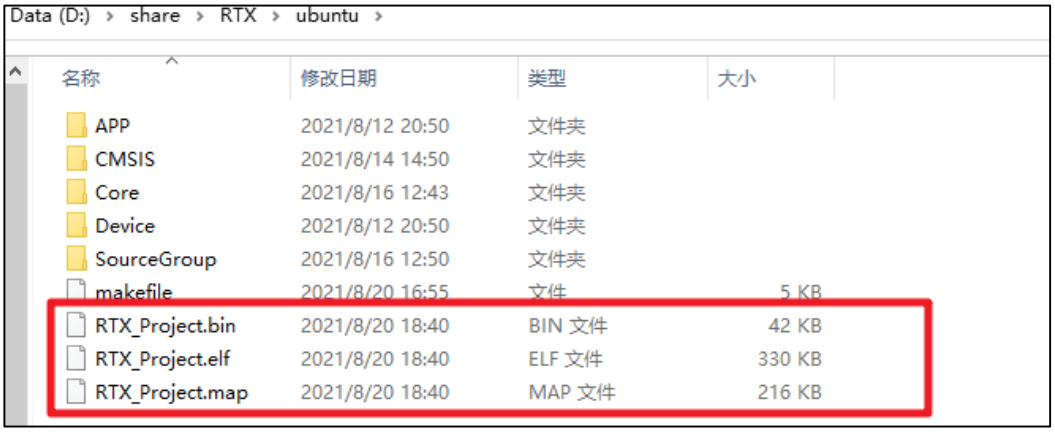
在顶层 makefile 所在目录执行命令：make

图 3-5. Mak 执行结果

```
 -o Device/source/system_gd32f30x.o Device/source/system_gd32f30x.c
In file included from /mnt/hgfs/share-2/RTX/ubuntu/Core/include/core_cm4.h:188:0,
                 from /mnt/hgfs/share-2/RTX/ubuntu/Device/include/gd32f30x.h:258,
                 from Device/source/system_gd32f30x.c:36:
/mnt/hgfs/share-2/RTX/ubuntu/Core/include/core_cmFunc.h: In function '__set_FPSCR':
/mnt/hgfs/share-2/RTX/ubuntu/Core/include/core_cmFunc.h:592:78: warning: unused parameter 'fpscr' [-Wunused-paramet
er]
 __attribute__( ( always_inline ) ) __STATIC_INLINE void __set_FPSCR(uint32_t fpscr)
                                                                              ^
编译.o目标文件
arm-none-eabi-gcc            -c -W -Wall -g -mcpu=cortex-m4 -mthumb -D GD32F30X_HD -D USE_STDPERIPH_DRIVER -I/mnt/h
gfs/share-2/RTX/ubuntu/Device/include -I/mnt/hgfs/share-2/RTX/ubuntu/Core/include -I/mnt/hgfs/share-2/RTX/ubuntu/AP
P/include -I/mnt/hgfs/share-2/RTX/ubuntu/Stdlib/include -I/mnt/hgfs/share-2/RTX/ubuntu/CMSIS/include -O0 -std=gnu11
 -o SourceGroup/source/main.o SourceGroup/source/main.c
In file included from /mnt/hgfs/share-2/RTX/ubuntu/Core/include/core_cm4.h:188:0,
                 from /mnt/hgfs/share-2/RTX/ubuntu/Device/include/gd32f30x.h:258,
                 from SourceGroup/source/main.c:6:
/mnt/hgfs/share-2/RTX/ubuntu/Core/include/core_cmFunc.h: In function '__set_FPSCR':
/mnt/hgfs/share-2/RTX/ubuntu/Core/include/core_cmFunc.h:592:78: warning: unused parameter 'fpscr' [-Wunused-paramet
er]
 __attribute__( ( always_inline ) ) __STATIC_INLINE void __set_FPSCR(uint32_t fpscr)
                                                                              ^
SourceGroup/source/main.c: In function 'app_main':
SourceGroup/source/main.c:17:22: warning: unused parameter 'argument' [-Wunused-parameter]
 void app_main (void *argument) {
                     ^
arm-none-eabi-gcc            -c -mthumb -mcpu=cortex-m4 -g -Wa,--warn  -o CMSIS/source/../GCC/irq_cm3.o CMSIS/sourc
e/../GCC/irq_cm3.s
arm-none-eabi-gcc            -c -mthumb -mcpu=cortex-m4 -g -Wa,--warn  -o Device/source/startup_gd32f30x_hd.o Devic
e/source/startup_gd32f30x_hd.s
格式转换为bin文件
arm-none-eabi-gcc            APP/source/gd32f307c_eval.o CMSIS/source/os_systick.o CMSIS/source/RTX_Config.o CMSIS/
source/rtx_delay.o CMSIS/source/rtx_evflags.o CMSIS/source/rtx_evr.o CMSIS/source/rtx_kernel.o CMSIS/source/rtx_lib
.o CMSIS/source/rtx_memory.o CMSIS/source/rtx_mempool.o CMSIS/source/rtx_msgqueue.o CMSIS/source/rtx_mutex.o CMSIS/
source/rtx_semaphore.o CMSIS/source/rtx_system.o CMSIS/source/rtx_thread.o CMSIS/source/rtx_timer.o Device/source/g
d32f30x_eval.o Device/source/gd32f30x_gpio.o Device/source/gd32f30x_rcu.o Device/source/system_gd32f30x.o SourceGro
up/source/main.o  CMSIS/source/../GCC/irq_cm3.o Device/source/startup_gd32f30x_hd.o -TDevice/source/gd32f30x_flash.
ld -o RTX_Project.elf -mthumb -mcpu=cortex-m4 -Wl,--start-group -lc -lm -Wl,--end-group -specs=nosys.specs -static
-Wl,-cref,-u,Reset_Handler -Wl,-Map=RTX_Project.map -Wl,--gc-sections -Wl,--defsym=malloc_getpagesize_P=0x80
arm-none-eabi-objcopy RTX_Project.elf  RTX_Project.bin -Obinary
root@xunshi-virtual-machine:/mnt/hgfs/share-2/RTX/ubuntu# ~
```

编译成功之后在 makefile 同级目录下会产生编译出的.bin 文件，.elf 文件和.map 文件。

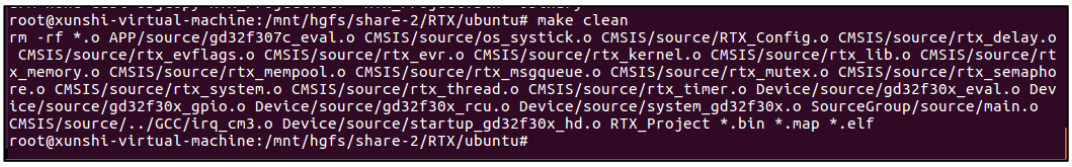
图 3-6. 顶层 makefile 所在目录



在 makefile 目录下执行命令：make clean

会发现之前执行 make 命令生成的.bin 文件，.elf 文件和.map 文件都已被删除。

图 3-7. Make clean 执行结果



最后为了验证编译出来的固件是否可以正常运行，使用 SEGGR J-Flash 将编译出的.bin 文件烧写进 MCU 进行测试。观察 LED 灯可正常运行。

4. 版本历史

表 4-1. 版本历史

版本号.	说明	日期
1.0	首次发布	2021 年 8 月 26 日

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